FIG. 1

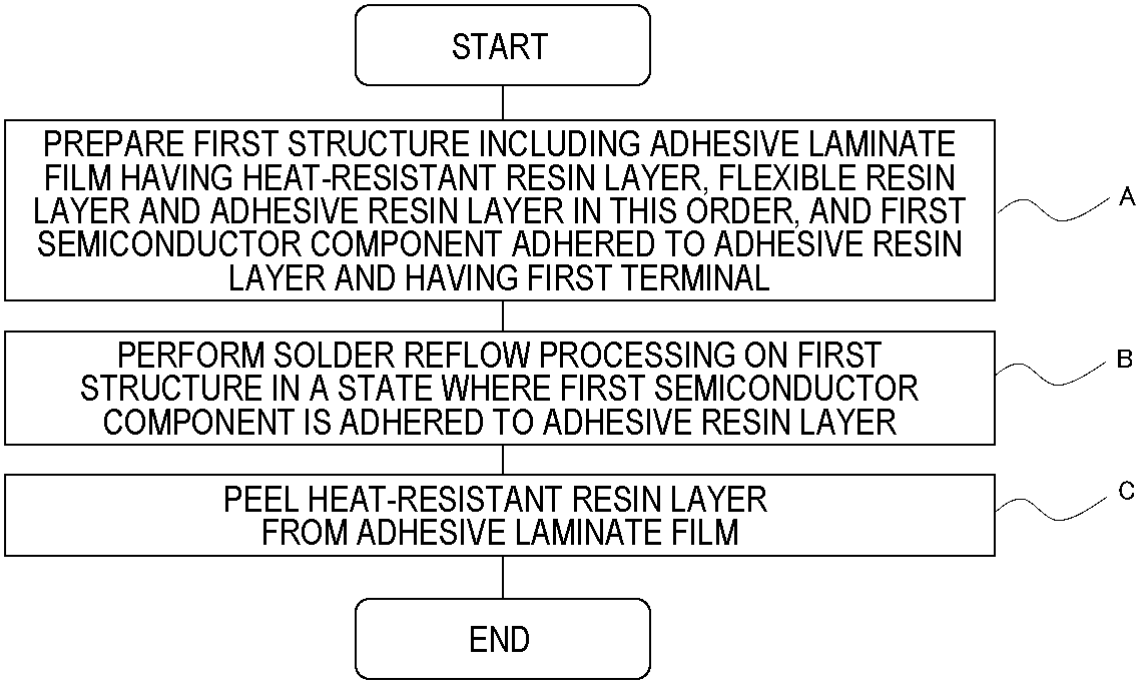

START
PREPARE FIRST STRUCTURE INCLUDING ADHESIVE LAMINATE FILM HAVING HEAT-RESISTANT RESIN LAYER, FLEXIBLE RESIN LAYER AND ADHESIVE RESIN LAYER IN THIS ORDER, AND FIRST SEMICONDUCTOR COMPONENT ADHERED TO ADHESIVE RESIN LAYER AND HAVING FIRST TERMINAL
A
PERFORM SOLDER REFLOW PROCESSING ON FIRST STRUCTURE IN A STATE WHERE FIRST SEMICONDUCTOR COMPONENT IS ADHERED TO ADHESIVE RESIN LAYER
B
PEEL HEAT-RESISTANT RESIN LAYER FROM ADHESIVE LAMINATE FILM
C
END

FIG. 2

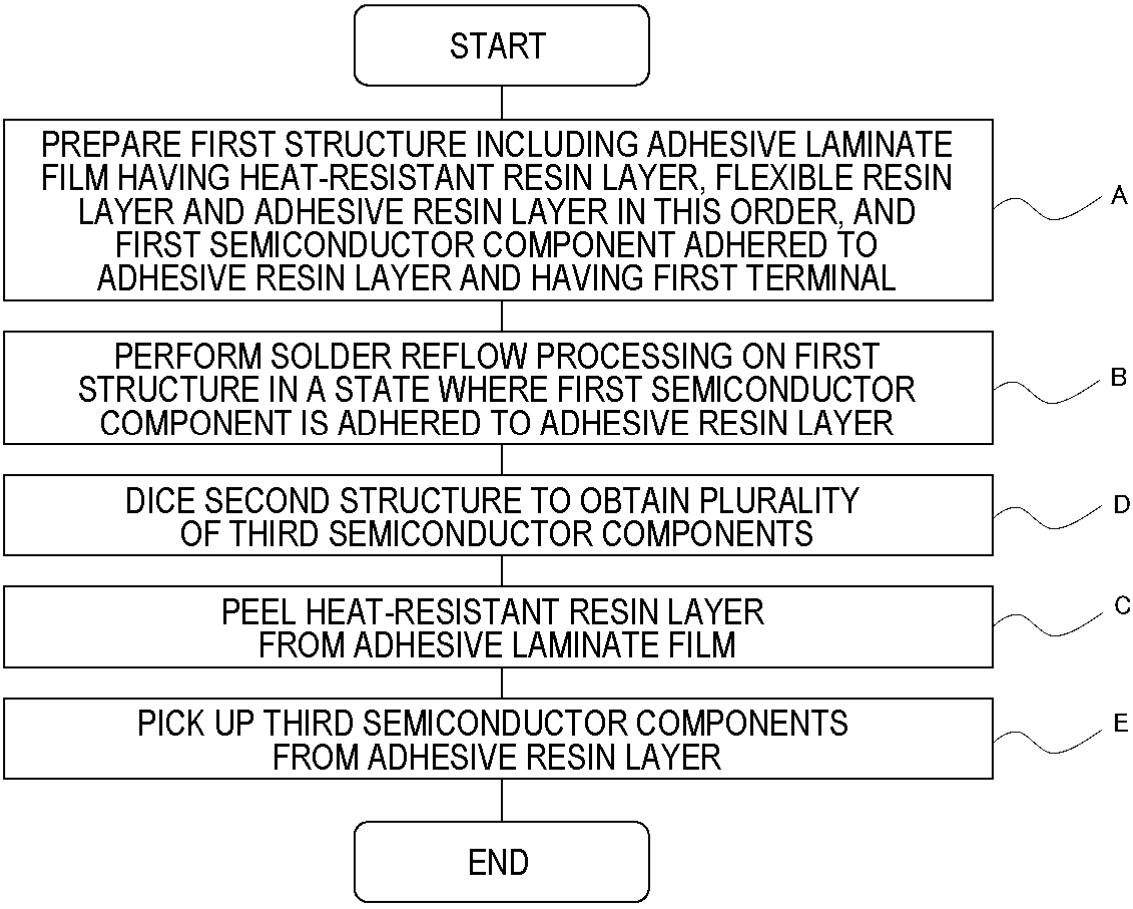

START
PREPARE FIRST STRUCTURE INCLUDING ADHESIVE LAMINATE FILM HAVING HEAT-RESISTANT RESIN LAYER, FLEXIBLE RESIN LAYER AND ADHESIVE RESIN LAYER IN THIS ORDER, AND FIRST SEMICONDUCTOR COMPONENT ADHERED TO ADHESIVE RESIN LAYER AND HAVING FIRST TERMINAL
A
PERFORM SOLDER REFLOW PROCESSING ON FIRST STRUCTURE IN A STATE WHERE FIRST SEMICONDUCTOR COMPONENT IS ADHERED TO ADHESIVE RESIN LAYER
B
DICE SECOND STRUCTURE TO OBTAIN PLURALITY OF THIRD SEMICONDUCTOR COMPONENTS
D
PEEL HEAT-RESISTANT RESIN LAYER FROM ADHESIVE LAMINATE FILM
C
PICK UP THIRD SEMICONDUCTOR COMPONENTS FROM ADHESIVE RESIN LAYER
E
END

FIG. 3

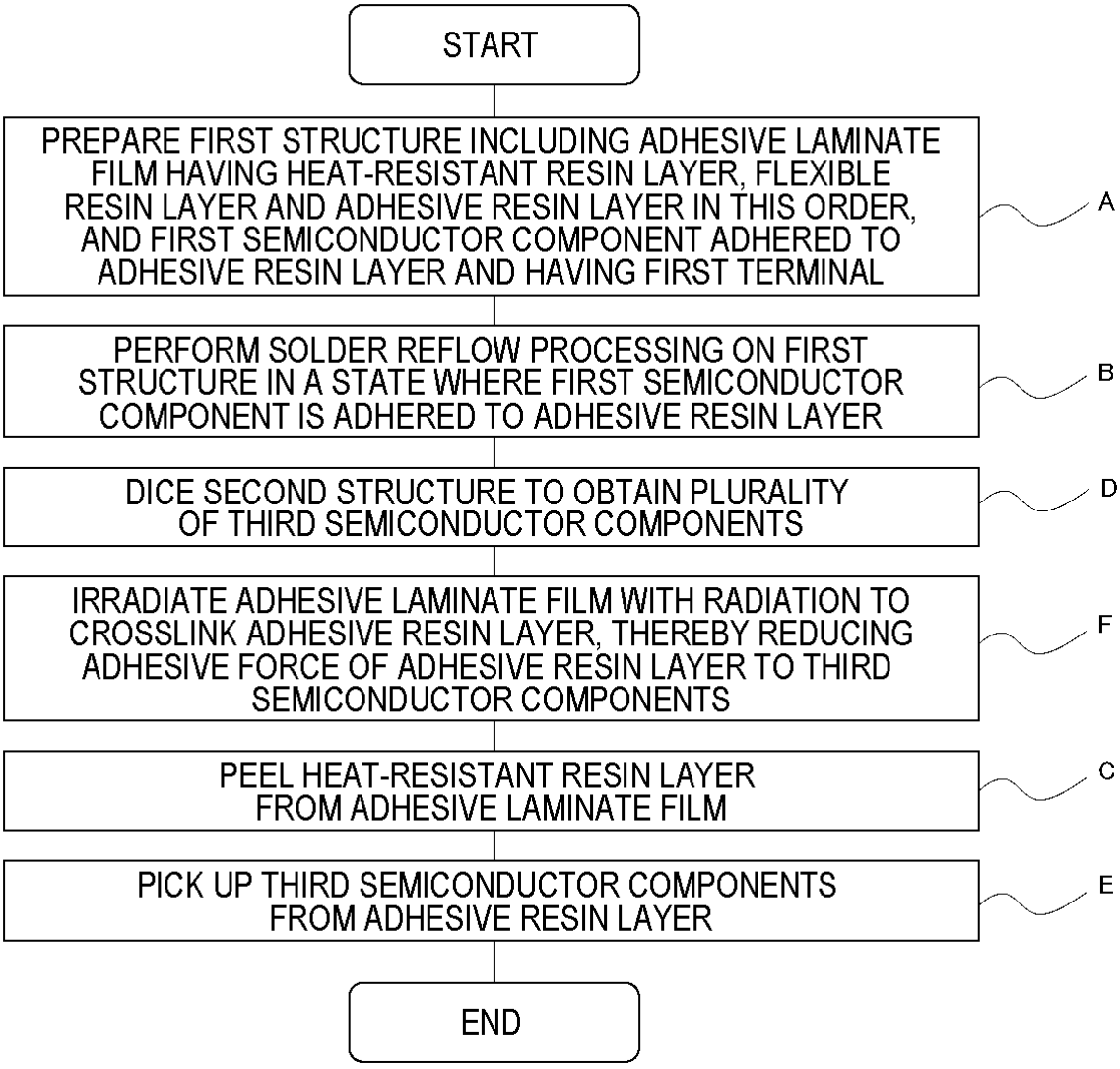

START
PREPARE FIRST STRUCTURE INCLUDING ADHESIVE LAMINATE FILM HAVING HEAT-RESISTANT RESIN LAYER, FLEXIBLE RESIN LAYER AND ADHESIVE RESIN LAYER IN THIS ORDER, AND FIRST SEMICONDUCTOR COMPONENT ADHERED TO ADHESIVE RESIN LAYER AND HAVING FIRST TERMINAL
A
PERFORM SOLDER REFLOW PROCESSING ON FIRST STRUCTURE IN A STATE WHERE FIRST SEMICONDUCTOR COMPONENT IS ADHERED TO ADHESIVE RESIN LAYER
B
DICE SECOND STRUCTURE TO OBTAIN PLURALITY OF THIRD SEMICONDUCTOR COMPONENTS
D
IRRADIATE ADHESIVE LAMINATE FILM WITH RADIATION TO CROSSLINK ADHESIVE RESIN LAYER, THEREBY REDUCING ADHESIVE FORCE OF ADHESIVE RESIN LAYER TO THIRD SEMICONDUCTOR COMPONENTS
F
PEEL HEAT-RESISTANT RESIN LAYER FROM ADHESIVE LAMINATE FILM
C
PICK UP THIRD SEMICONDUCTOR COMPONENTS FROM ADHESIVE RESIN LAYER
E
END

FIG. 4

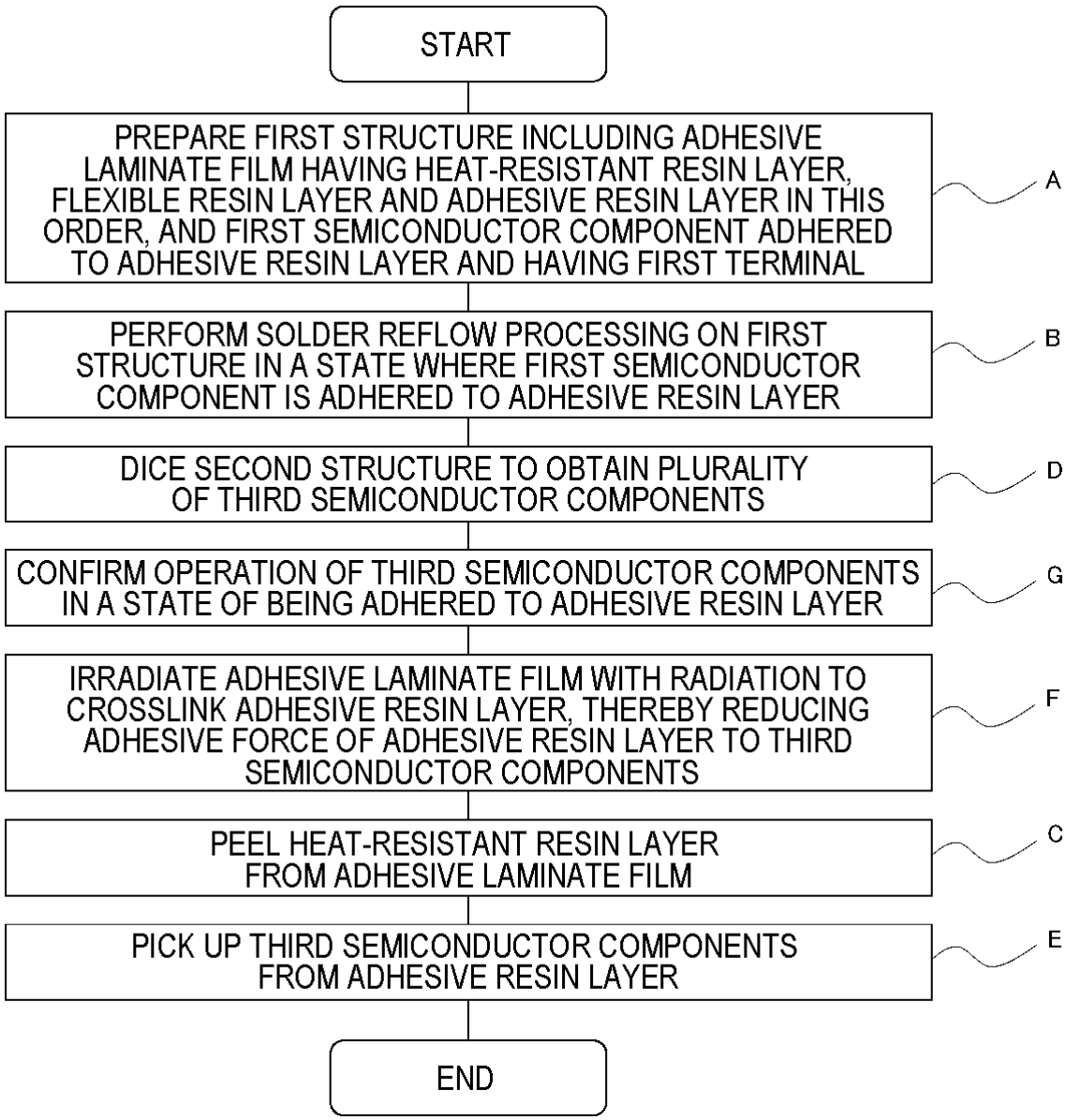

START
PREPARE FIRST STRUCTURE INCLUDING ADHESIVE LAMINATE FILM HAVING HEAT-RESISTANT RESIN LAYER, FLEXIBLE RESIN LAYER AND ADHESIVE RESIN LAYER IN THIS ORDER, AND FIRST SEMICONDUCTOR COMPONENT ADHERED TO ADHESIVE RESIN LAYER AND HAVING FIRST TERMINAL
A
PERFORM SOLDER REFLOW PROCESSING ON FIRST STRUCTURE IN A STATE WHERE FIRST SEMICONDUCTOR COMPONENT IS ADHERED TO ADHESIVE RESIN LAYER
B
DICE SECOND STRUCTURE TO OBTAIN PLURALITY OF THIRD SEMICONDUCTOR COMPONENTS
D
CONFIRM OPERATION OF THIRD SEMICONDUCTOR COMPONENTS IN A STATE OF BEING ADHERED TO ADHESIVE RESIN LAYER
G
IRRADIATE ADHESIVE LAMINATE FILM WITH RADIATION TO CROSSLINK ADHESIVE RESIN LAYER, THEREBY REDUCING ADHESIVE FORCE OF ADHESIVE RESIN LAYER TO THIRD SEMICONDUCTOR COMPONENTS
F
PEEL HEAT-RESISTANT RESIN LAYER FROM ADHESIVE LAMINATE FILM
C
PICK UP THIRD SEMICONDUCTOR COMPONENTS FROM ADHESIVE RESIN LAYER
E
END

FIG. 5

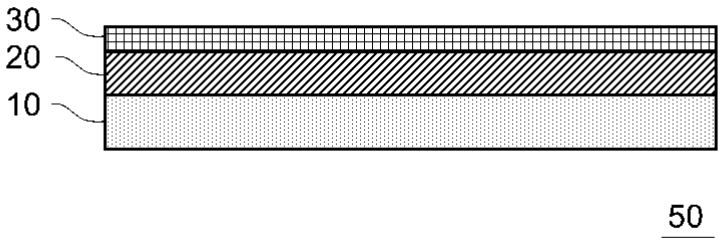
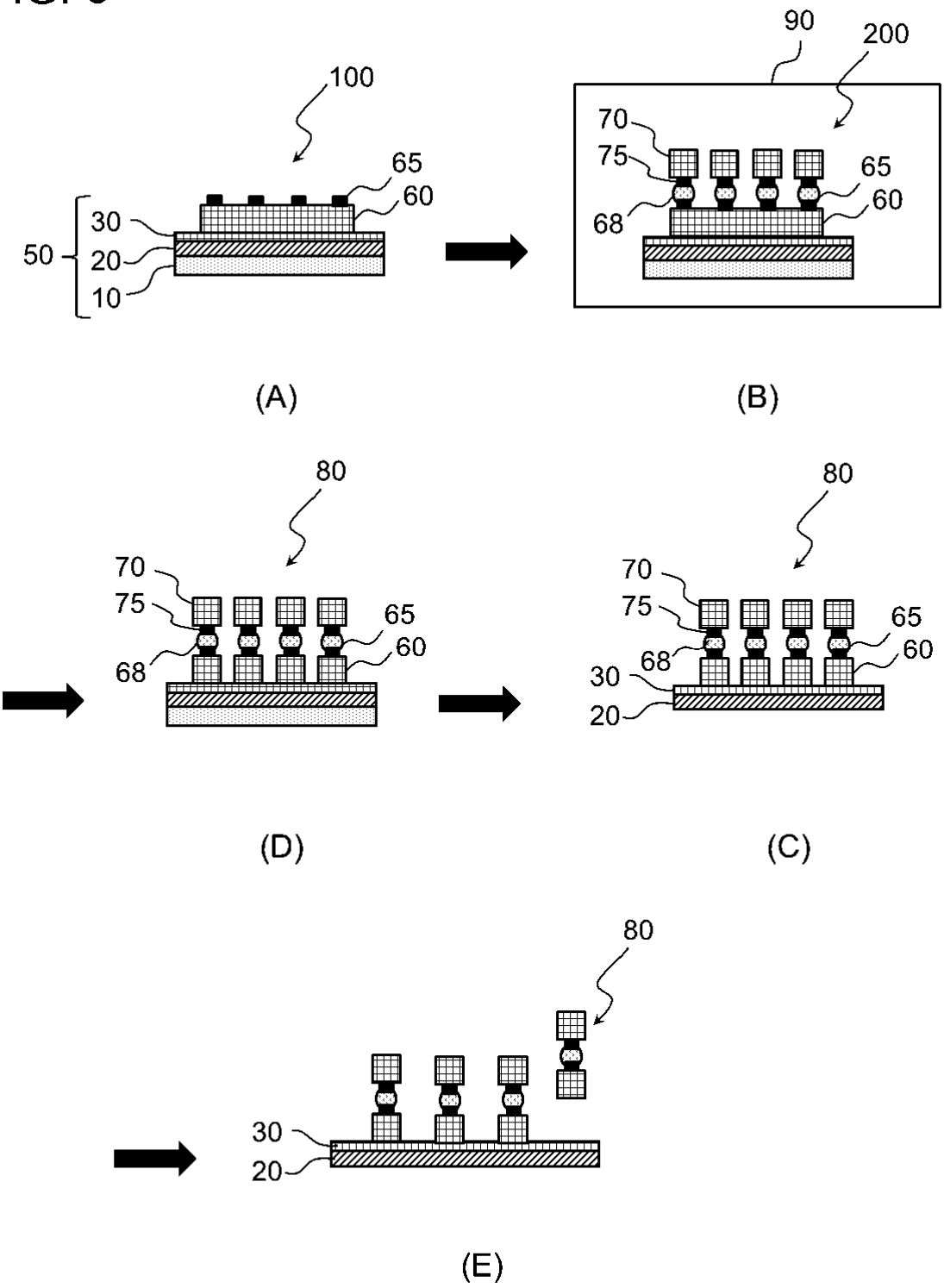


FIG. 6


100
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68
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(C)
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(E)
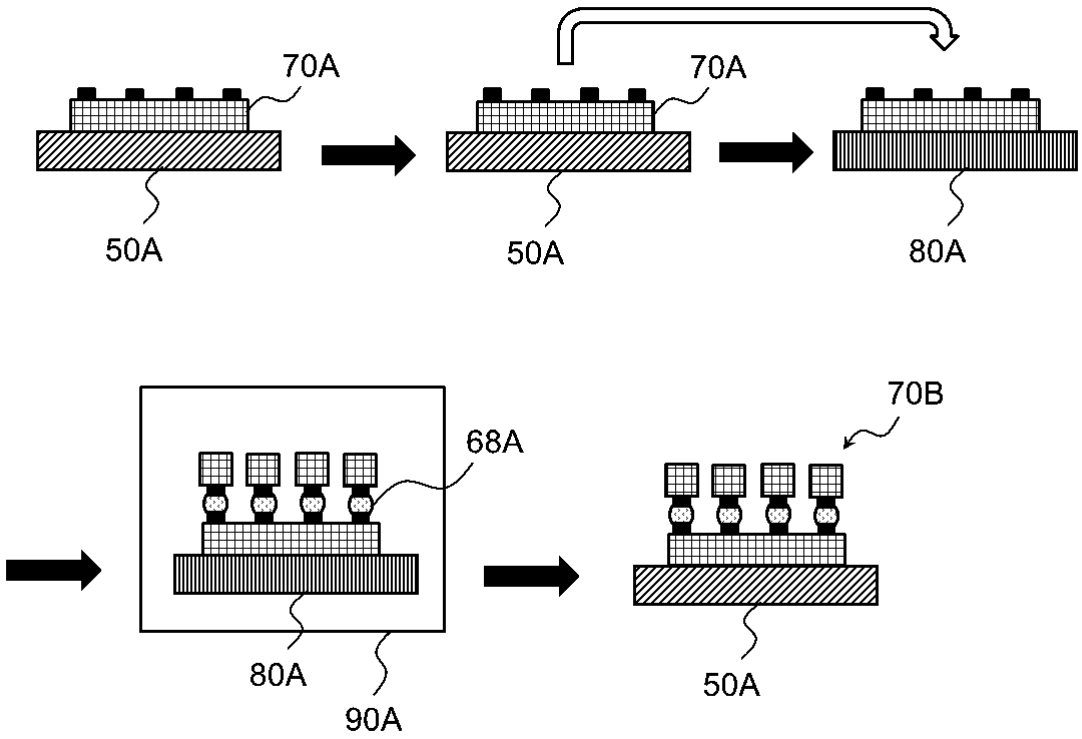
FIG. 7